

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Original) Use of an article whose surface exhibits a composite material in full or in parts, the composite material consisting of a non-metallic substrate containing at least one polymer, and a metallic layer present thereon and deposited without external current, having an adhesive strength of at least 4 N/mm^2 , as electronic structural part.
2. (Original) Use according to claim 1 characterised in that the standard deviation of the adhesive strength at six different measured value points distributed over the surface of the composite material is maximum 25 % of the arithmetic mean.
3. (Currently Amended) Use according to claim 1 [[or 2]] characterised in that
 - a) the surface of the article is not chemically pretreated before the application of the metallic layer deposited without electric current; and
 - b) the metallic layer is not applied by thermal spraying, CVD, PVD or laser treatment.
4. (Currently Amended) Use according to claim 1 ~~one of claims 1 to 3~~ characterised in that the non-metallic substrate is the surface of the article.
5. (Currently Amended) Use according to claim 1 ~~one of claims 1 to 3~~ characterised in that the non-metallic substrate not the surface of the article.
6. (Currently Amended) Use according to claim 1 ~~one of the preceding claims~~ characterised in that the boundary present between the non-metallic substrate and the metallic layer exhibits a roughness with an R_z value of maximum $35 \text{ }\mu\text{m}$.

7. (Currently Amended) Use according to claim 1 ~~one of the preceding claims~~ characterised in that the boundary present between the non-metallic substrate and the metallic layer exhibits a roughness with an R_a value of maximum 5 μm .

8. (Currently Amended) Use according to claim 1 ~~one of the preceding claims~~ characterised in that the non-metallic substrate contains at least one fibre-reinforced polymer, in particular a polymer reinforced with carbon fibre and the diameter of the fibre is less than 10 μm .

9. (Currently Amended) Use according to claim 1 ~~one of claims 1 to 5~~ characterised in that the non-metallic substrate contains at least one fibre-reinforced polymer, in particular a polymer reinforced with glass fibre and the diameter of the fibre is more than 10 μm .

10. (Original) Use according to claim 9 characterised in that the boundary present between the non-metallic substrate and the metallic layer exhibits a roughness with an R_a value of maximum 10 μm .

11. (Currently Amended) Use according to claim 9 ~~one of claims 9 or 10~~ characterised in that the boundary present between the non-metallic substrate and the metallic layer exhibits a roughness with an R_z value of maximum 100 μm .

12. (Currently Amended) Use according to claim 1 ~~one of preceding claims~~ characterised in that the polymer is selected from the group of polyamide, polyvinyl chloride, polystyrene, epoxy resin, polyether ether ketone, polyoxymethylene, polyformaldehyde, polyacetal, polyurethane, polyether imide, polyphenyl sulphone, polyphenylene sulphide, polyarylamide, polycarbonate and polyimide.

13. (Original) Use according to claim 12 characterised in that the metallic layer exhibits an adhesive strength of at least 12 N/mm^2

14. (Currently Amended) Use according to claim 1 ~~one of claims 1 to 11~~ characterised in that the non-metallic substrate is polypropylene or polytetrafluoroethylene,

15. (Currently Amended) Use according to claim 1 ~~one of the preceding claims~~ characterised in that the standard deviation of the adhesive strength amounts to maximum 25 %, in particular maximum 15 %, of the arithmetic mean.

16. (Currently Amended) Use according to claim 1 ~~one of the preceding claims~~ characterised in that the metal layer deposited without electric current is a metal alloy or metal dispersion layer.

17. (Currently Amended) Use according to claim 1 ~~one of the preceding claims~~ characterised in that the metal layer deposited without external current is a copper, nickel or gold layer.

18. (Currently Amended) Use according to claim 1 one of the preceding claims characterised in that the metal dispersion layer deposited without external current is a copper, nickel or gold layer with embedded non-metallic particles.

19. (Original) Use according to claim 18 characterised in that the non-metallic particles exhibit a hardness of more than 1,500 HV and are selected from the group of silicon carbide, corundum, diamond and tetraboron carbide.

20. (Currently Amended) Use according to claim 18 [[or 19]] characterised in that the non-metallic particles exhibit friction-reducing properties and are selected from the group of polytetrafluoroethylene, molybdenum sulphide, cubic boron nitride and tin sulphide.

21. (Currently Amended) Use according to claim 1 ~~one of the preceding claims~~ characterised in that, onto the metallic layer deposited without external current, a layer of aluminium, titanium or their alloys is applied whose surface is anodically oxidised or ceramics-treated.

22. (Original) Use according to claim 21 characterised in that one or several metallic layers are also arranged between the metallic layer deposited without external current and the layer of aluminium, titanium or their alloys.

23. (Currently Amended) Use according to claim 21 ~~[[or 22]]~~ characterised in that the surface of the article is a ceramic oxide layer of aluminium, titanium or their alloys, which layer is coloured black by foreign ion embeddings.

24. (Currently Amended) Use according to claim 1 ~~one of the preceding claims~~ as condenser, sonic field condenser, high frequency structural part, antenna, antenna housing, sonic rider or microwave hollow-cored conductor or circuit breaker surface.